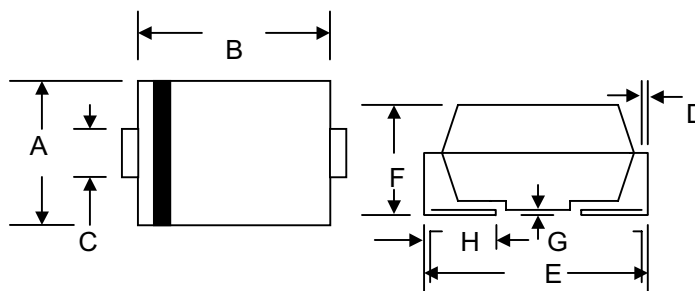


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**Features**

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 30A Peak
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O



**Mechanical Data**

- Case: Low Profile Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.064 grams (approx.)

SMA/DO-214AC		
Dim	Min	Max
A	0.098(2.50)	0.114(2.90)
B	0.157(4.00)	0.181(4.60)
C	0.055(1.40)	0.063(1.60)
D	0.006(0.15)	0.012(0.31)
E	0.189(4.80)	0.208(5.28)
F	0.079(2.00)	0.096(2.44)
G	0.002(0.05)	0.008(0.20)
H	0.030(0.76)	0.060(1.52)
All Dimensions in inch(mm)		

**Maximum Ratings and Electrical Characteristics @<sub>TA</sub>=25°C unless otherwise specified**

Characteristic	Symbol	SS12	SS13	SS14	SS15	SS16	SS18	SS19	S100	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>									
Working Peak Reverse Voltage	V <sub>RWM</sub>	20	30	40	50	60	80	90	100	V
DC Blocking Voltage	V <sub>R</sub>									
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	21	28	35	42	56	64	71	V
Average Rectified Output Current @ <sub>T<sub>L</sub></sub> = 130°C	I <sub>o</sub>	1.0								A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	30								A
Forward Voltage @ <sub>I<sub>F</sub></sub> = 1.0A	V <sub>FM</sub>	0.50			0.70		0.85			V
Peak Reverse Current @ <sub>T<sub>A</sub></sub> = 25°C	I <sub>RM</sub>	0.5								mA
At Rated DC Blocking Voltage @ <sub>T<sub>A</sub></sub> = 100°C		10								
Typical Thermal Resistance Junction to Ambient (Note 1)	R <sub>θJA</sub>	88								°C/W
Operating Temperature Range	T <sub>J</sub>	-65 to +150								°C
Storage Temperature Range	T <sub>STG</sub>	-65 to +150								°C

Note: 1. Mounted on P.C. Board with 5.0mm<sup>2</sup> copper pad areas

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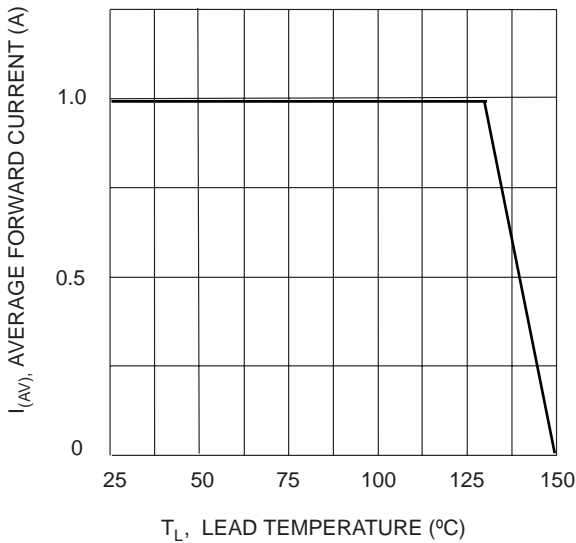


Fig. 1 Forward Current Derating Curve

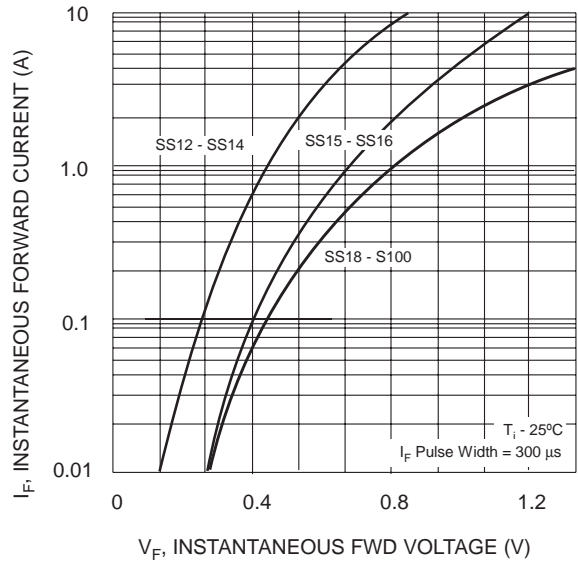


Fig. 2 Typ. Forward Characteristics

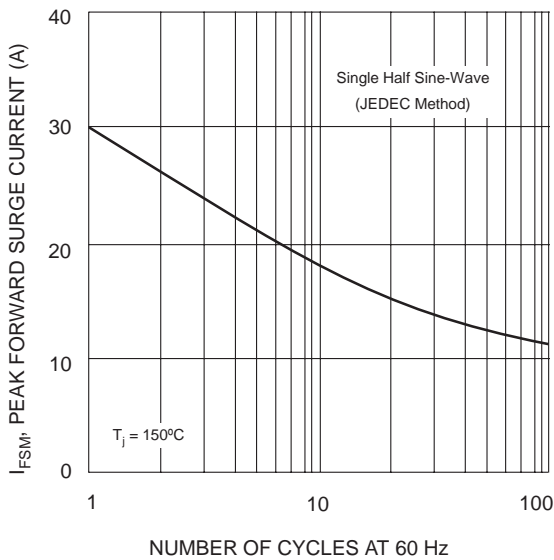


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

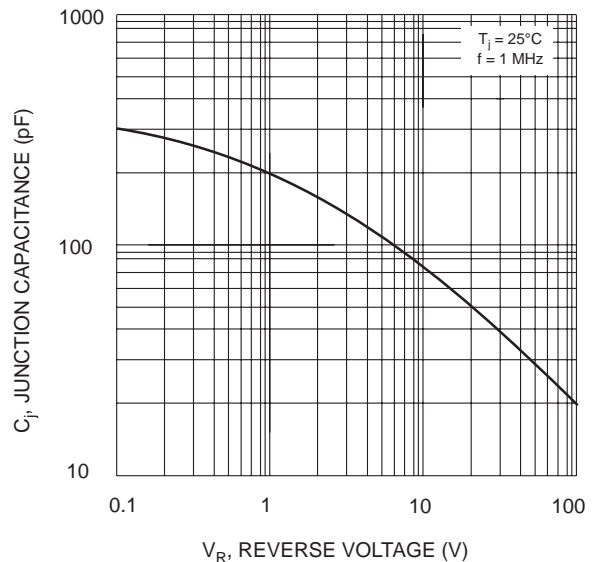


Fig. 4 Typical Junction Capacitance

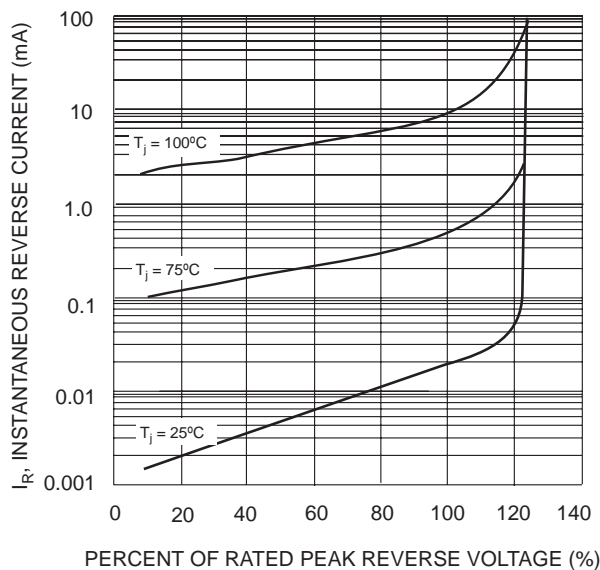


Fig. 5 Typical Reverse Characteristics

**TECHNICAL DATA**

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